AUTOMOTIVE

ROHS

HALOGEN

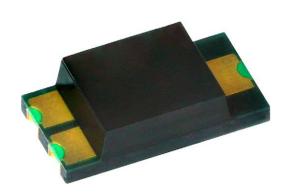
FREE GREEN

(5-2008)



Vishay Semiconductors

Silicon PIN Photodiode



DESCRIPTION

VEMD6160X01 is a high speed and high sensitive PIN photodiode with excellent I_{ra} linearity. It is a small surface mount device (SMD) including the chip with a 0.85 mm² sensitive area and a daylight blocking filter.

FEATURES

- Package type: surface mount
- Package form: 1206
- Dimensions (L x W x H in mm): 4 x 2 x 1.05
- Radiant sensitive area (in mm²): 0.85
- Daylight blocking filter
- · High photo sensitivity
- · High radiant sensitivity
- Excellent I_{ra} linearity
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 70^{\circ}$
- Floor life: 72 h, MSL 4, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · High speed photo detector
- · Small signal detection
- · Proximity sensors

PRODUCT SUMMARY				
COMPONENT	I _{ra} (μΑ)	φ (deg)	λ _{0.1} (nm)	
VEMD6160X01	5	± 70	700 to 1070	

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VEMD6160X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	1206		

Note

· MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	20	V	
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW	
Junction temperature		Tj	110	°C	
Operating temperature range		T _{amb}	-40 to +110	°C	
Storage temperature range		T _{stg}	-40 to +110	°C	
Soldering temperature	According to reflow solder profile fig. 8	T _{sd}	260	°C	
Thermal resistance junction / ambient	According to EIA / JESD51	R _{thJA}	270	K/W	

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V_{F}	-	0.85	1.1	V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	20	-	=	V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}	-	0.03	5	nA
Diode capacitance	V _R = 0 V, f = 1 MHz, E = 0	C _D	-	11	=	pF
	V _R = 5 V, f = 1 MHz, E = 0	C _D	-	4.6	=	pF
Open circuit voltage	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	Vo	-	360	=	mV
Temperature coefficient of Vo	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	TK _{Vo}	-	-3.1	=	mV/K
Short circuit current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	l _k	-	5	=	μΑ
Temperature coefficient of I _k	$E_e = 1 \text{ mW/cm}^2, \lambda = 835 \text{ nm}$	TK _{lk}	-	0.1	=	%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	3.5	5	6.5	μΑ
	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 890 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	-	7	=	μΑ
Angle of half sensitivity		φ	-	± 70	=	deg
Wavelength of peak sensitivity		λ_{p}	-	840	=	nm
Range of spectral bandwidth		λ _{0.1}	-	700 to 1070	-	nm
Rise time	$V_R = 10 \text{ V}, R_L = 50 \Omega, \lambda = 830 \text{ nm}$	t _r	-	60	=	ns
Fall time	$V_R = 10 \text{ V}, R_L = 50 \Omega, \lambda = 830 \text{ nm}$	t _f	-	50	=	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

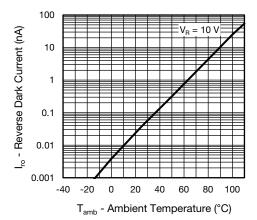


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

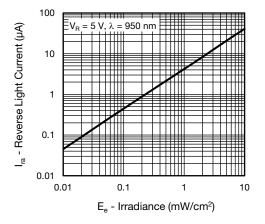


Fig. 3 - Reverse Light Current vs. Irradiance

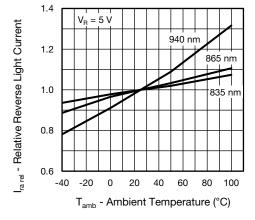


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

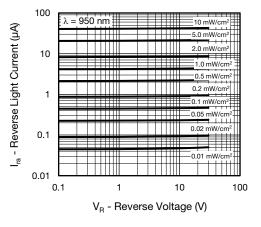


Fig. 4 - Reverse Light Current vs. Reverse Voltage

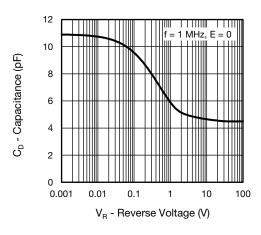


Fig. 5 - Diode Capacitance vs. Reverse Voltage

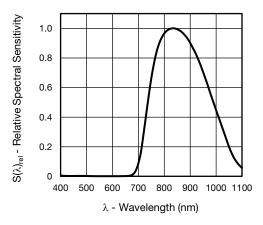


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

REFLOW SOLDER PROFILE

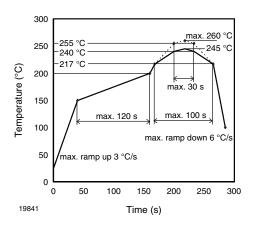


Fig. 8 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

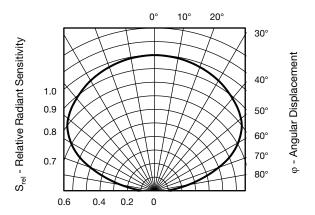


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 72 h

Conditions: T_{amb} < 30 °C, RH < 60 %

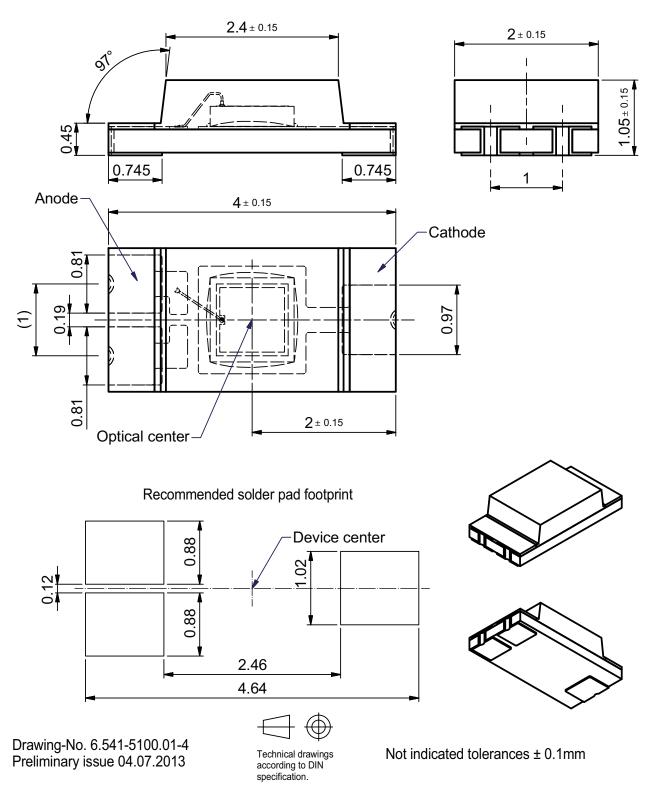
Moisture sensitivity level 4, according to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

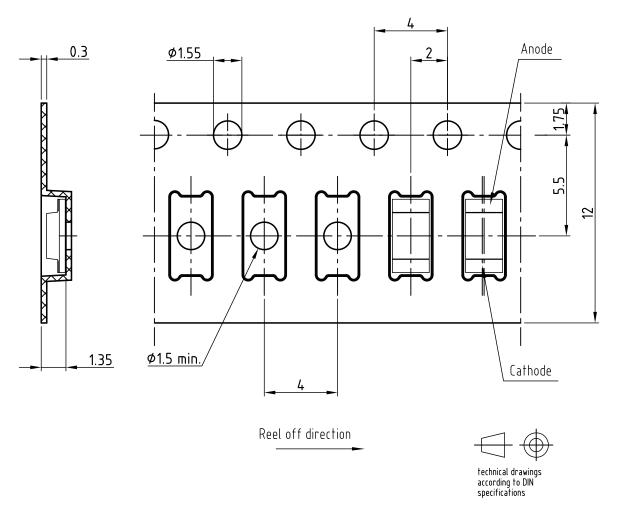


PACKAGE DIMENSIONS in millimeters





BLISTER TAPE DIMENSIONS in millimeters



Not indicated tolerances ±0.1

Drawing refers to following Types: TEMD6010FX01

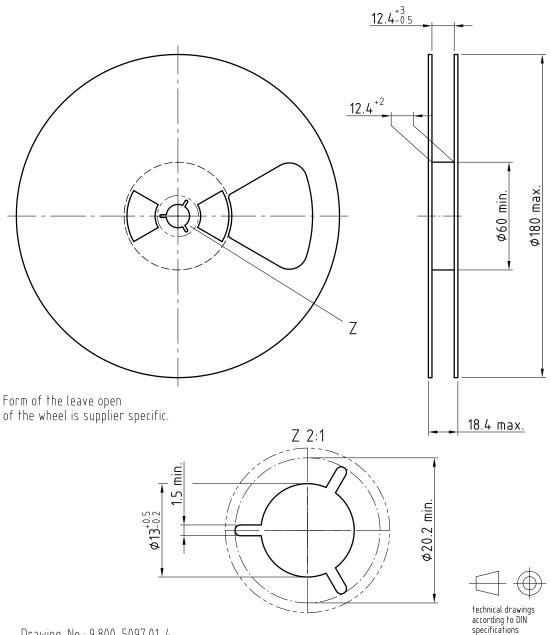
VEMD6x10X01 VEMD6x15X01

Drawing-No.: 9.700-5329.02-4

Prel Issue: 16.07.2013

All dimensions in mm

REEL DIMENSIONS in millimeters



Drawing-No.: 9.800-5097.01-4

Issue: 1; 05.05.08

20874



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